



Material Content Data Sheet



Sales Product Name		BTT6200-4ESA		Issued		4. July 2019		
MA#		MA002798008						
Package		PG-TSDSO-24-21		Weight*		111.75 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	2.840	2.54	2.54	25413	25413
leadframe	inorganic material	phosphorus	7723-14-0	0.016	0.01		142	
	non noble metal	zinc	7440-66-6	0.063	0.06		566	
	non noble metal	iron	7439-89-6	1.266	1.13		11326	
wire	non noble metal	copper	7440-50-8	51.392	46.00	47.20	459893	471927
	non noble metal	copper	7440-50-8	0.640	0.57	0.57	5730	5730
	encapsulation	organic material	carbon black	1333-86-4	0.152	0.14		1356
plastics		epoxy resin	-	5.909	5.29		52879	
	inorganic material	silicondioxide	60676-86-0	44.444	39.77	45.20	397720	451955
leadfinish	non noble metal	tin	7440-31-5	2.820	2.52	2.52	25236	25236
plating	noble metal	silver	7440-22-4	1.279	1.14	1.14	11445	11445
glue	plastics	epoxy resin	-	0.162	0.15		1451	
	noble metal	silver	7440-22-4	0.765	0.68	0.83	6843	8294
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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